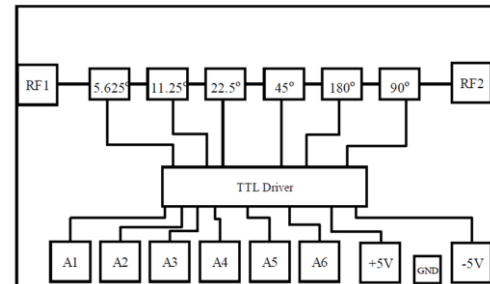


6 – 18GHz 6 BIT DIGITAL PHASE SHIFTER

Features

- ◆ Frequency Range: 6 – 18GHz
- ◆ Insertion Loss: < -18dB
- ◆ RMS Phase Error: < 8Deg
- ◆ RMS Amplitude Error: < 1dB
- ◆ Peak Phase Error: +3 to -15Deg
- ◆ Input & Output RL: -10dB Typ.
- ◆ On-chip TTL drivers
- ◆ Chip size: 5mm x 3.5mm x 0.1mm

Functional Diagram



Typical Applications

- ◆ Radar
- ◆ Military & Space
- ◆ Instrumentation

Description

The ASL 2020 is a wideband phase shifter operating in the 6-18GHz frequency range. The phase shifter features RMS phase error of less than 8deg over the operating frequency range. The phase shifter offers a mid-band insertion loss of 14dB and 10dB typical return loss over the operating bandwidth. The on-chip integrated TTL interface provides easy access to control the phase shift with a 6-bit digital control command. The TTL driver operates on +5/-5V supplies with minimal DC power consumption.

Absolute Maximum Ratings¹

Parameter	Absolute Maximum	Units
RF Input Power	20	dBm
Positive Supply Voltage	+6	V
Negative Supply Voltage	-6	V
Control Voltage	-0.5 to +5.5	V
Operating Temperature	-55 to +85	°C
Storage Temperature	-65 to +150	°C

1. Operation beyond these limits may cause permanent damage to the component

Electrical Specifications @ $T_A = 25\text{ }^{\circ}\text{C}$, $Z_0 = 50\Omega$

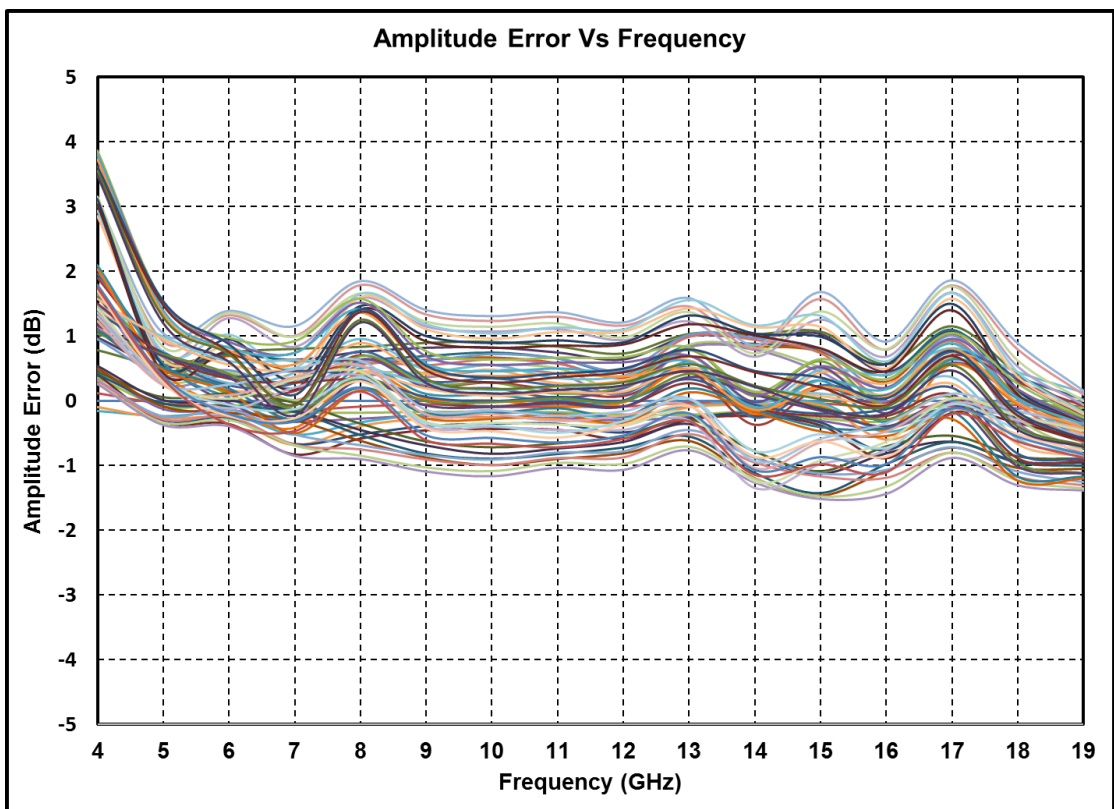
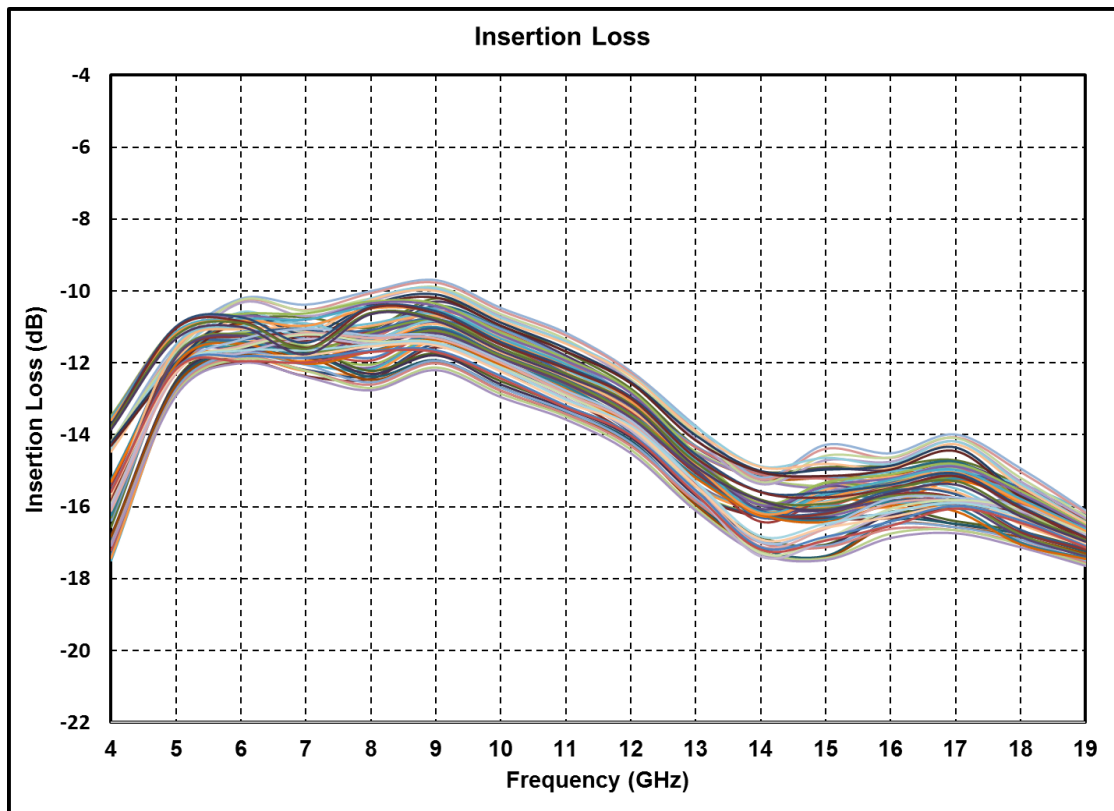
Parameter	Min.	Typ.	Max.	Units
Frequency Range	6.0-18.0			GHz
Phase Shift	0-360 in 64 steps			Deg.
Phase Resolution	5.625			Deg.
Insertion Loss	-18	-14	-9	dB
RMS Amplitude Error	0.4	0.7	1	dB
Peak Phase Error	+3 to -15			Deg.
RMS Phase Error (Calibrated)	1	3	4	Deg.
RMS Phase Error (Un-Calibrated)	2	5	8	
Input Return Loss	--	-10	-9	dB
Output Return Loss	--	-10	-6	dB
DC Supply	+5/-5			V
Control Voltages	TTL compatible			
ON	+3 to +5 V			V
OFF	0 to +0.5 V			V
Current ²	14			mA

Note:

1. The above mentioned electrical specifications are measured On-Wafer.
2. The current mentioned is overall current drawn on both +5V & -5V supply.

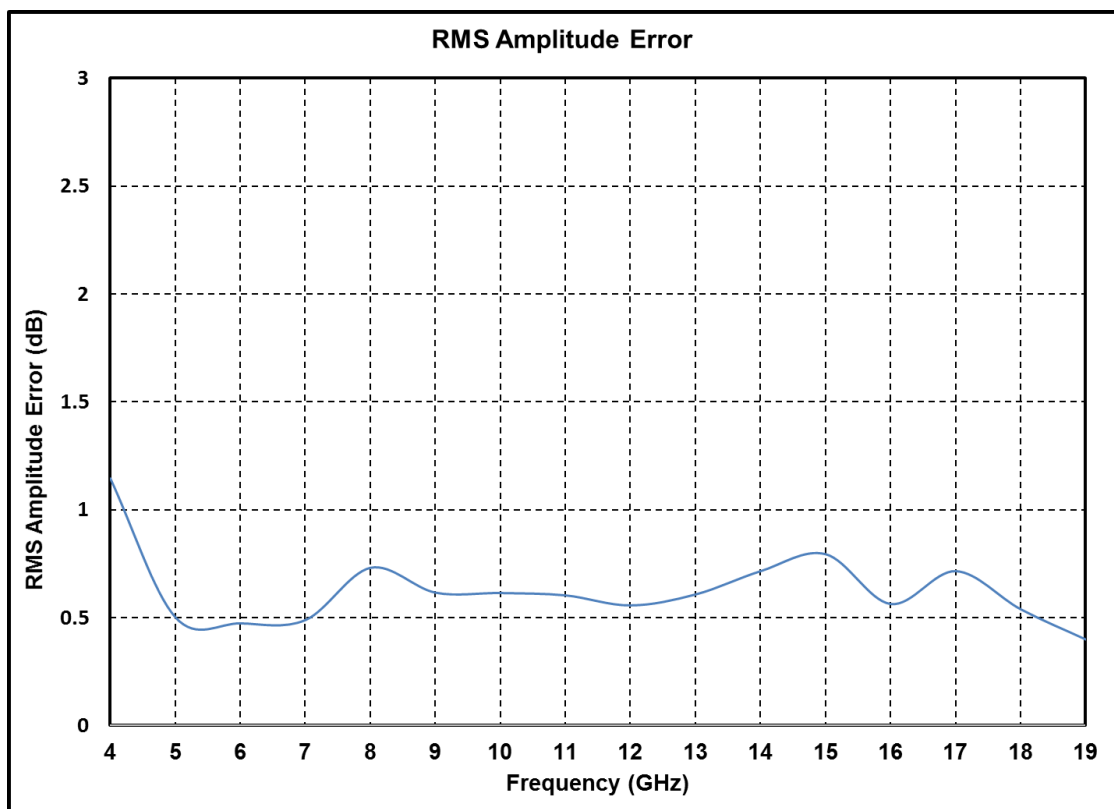
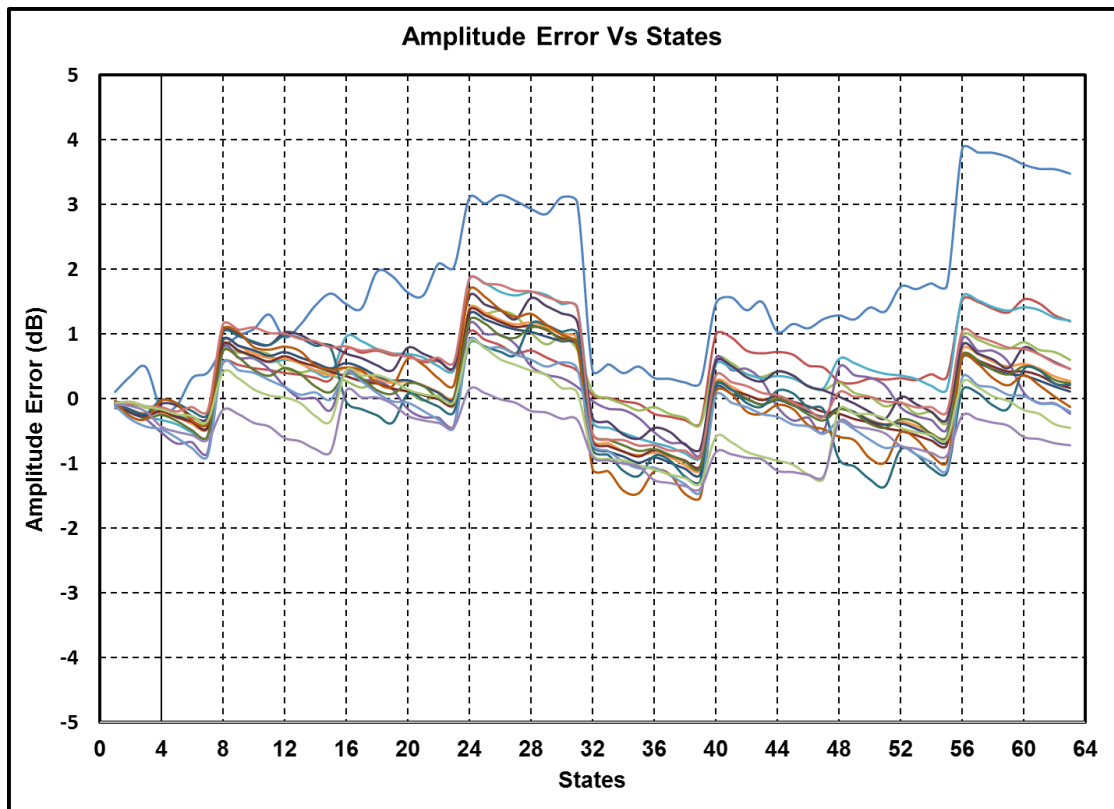
On Wafer data

Driver Bias +5V, -5V; Control Voltage 0/+5V; $T_A = 25^\circ\text{C}$



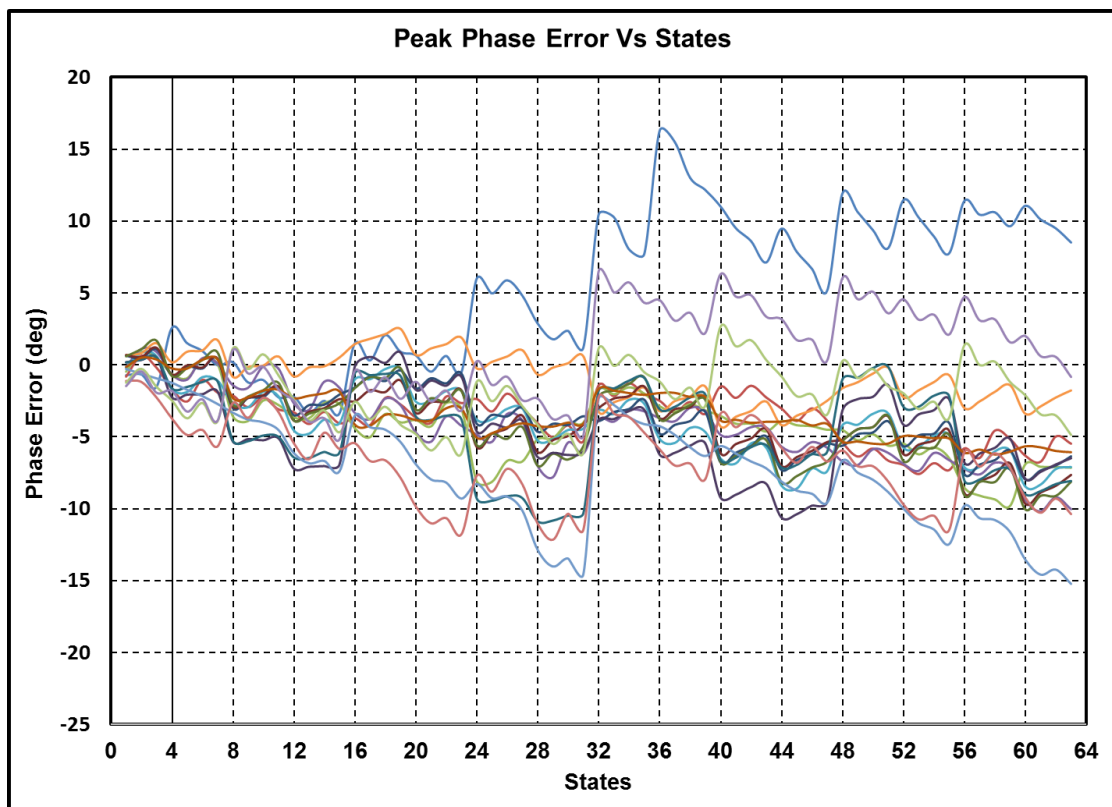
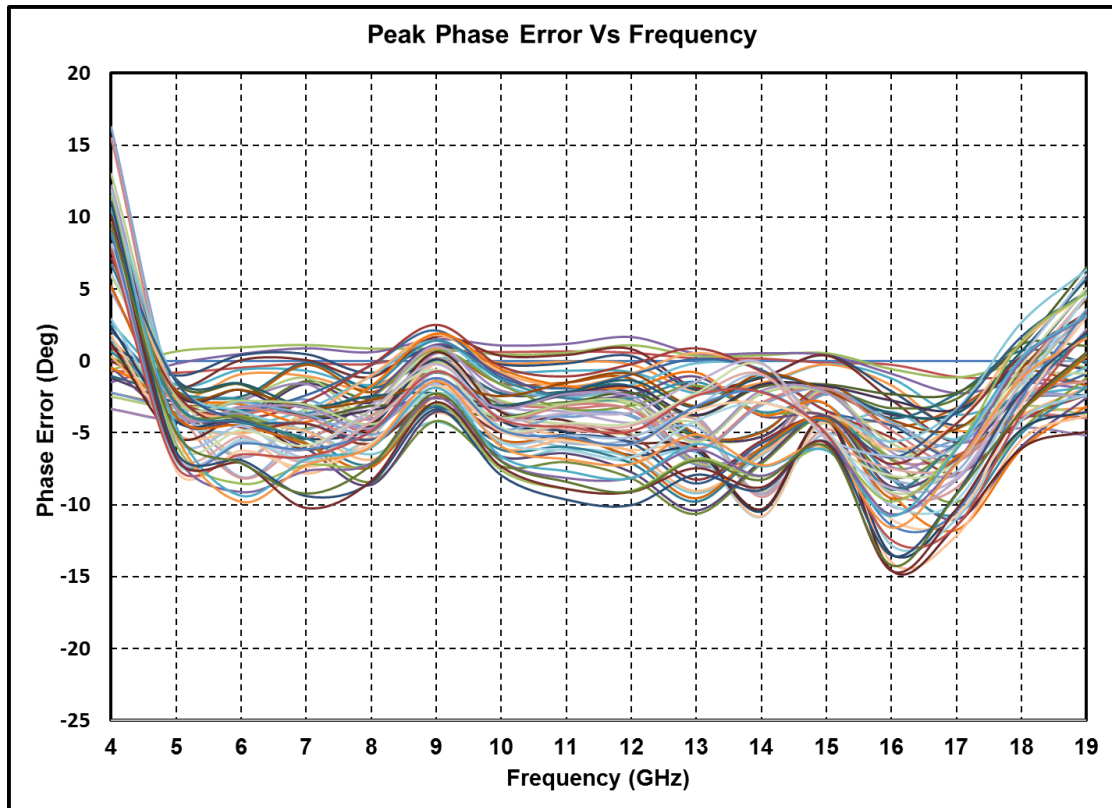
On Wafer data

Driver Bias +5V, -5V; Control Voltage 0/+5V; $T_A = 25^\circ\text{C}$



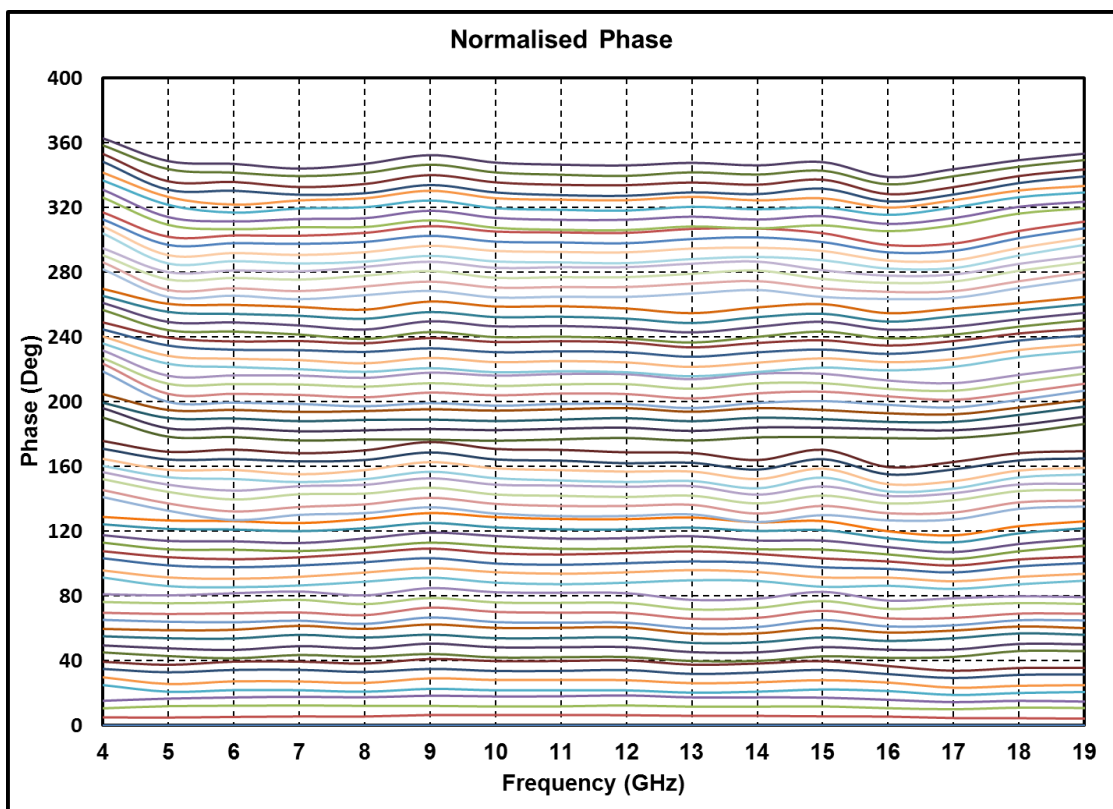
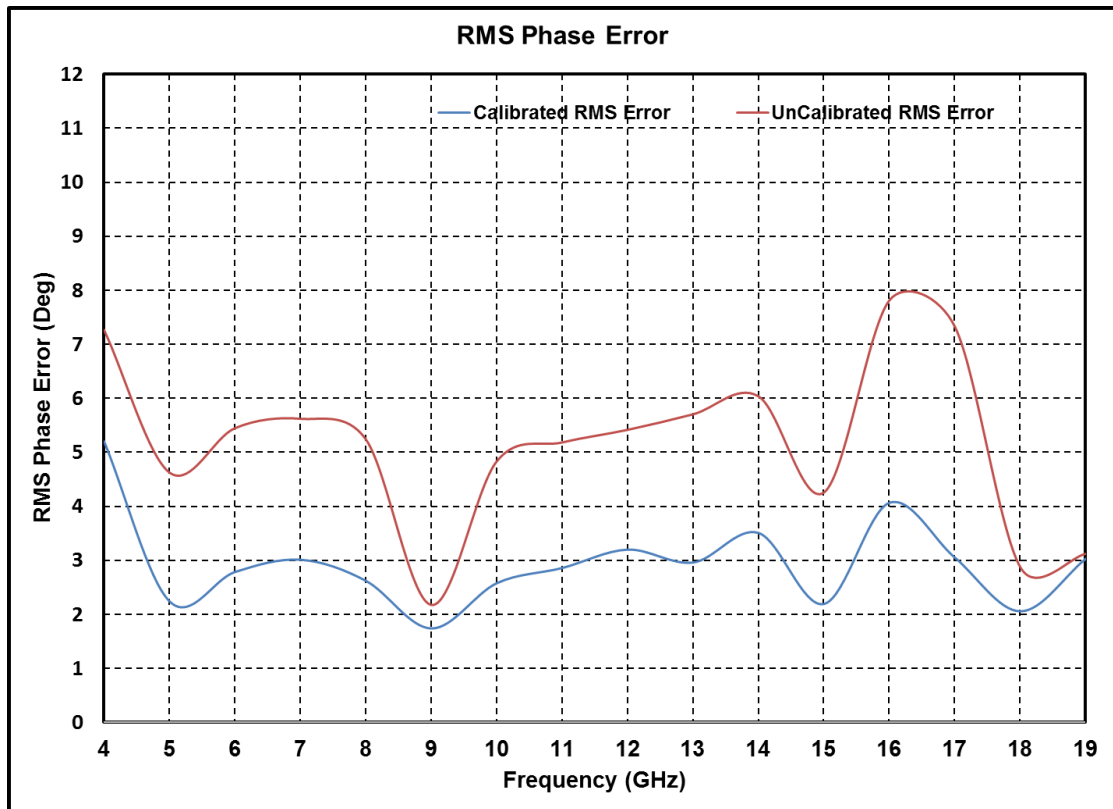
On Wafer data

Driver Bias +5V, -5V; Control Voltage 0/+5V; $T_A = 25^\circ\text{C}$



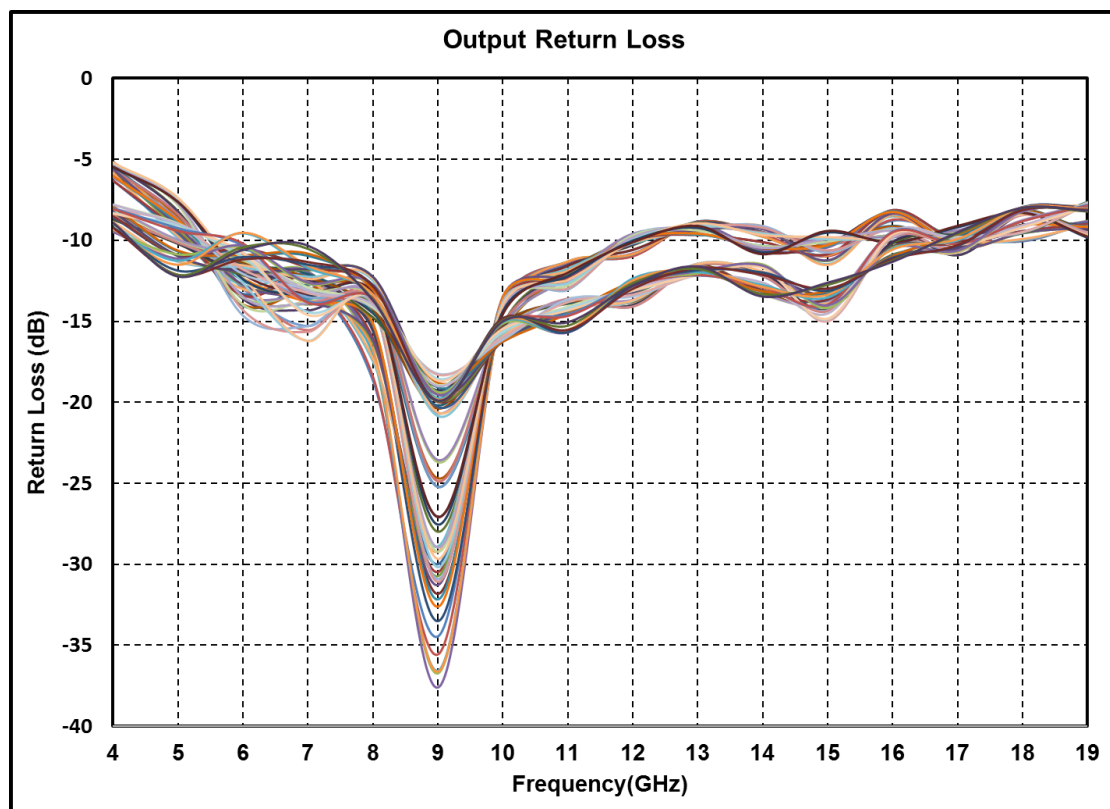
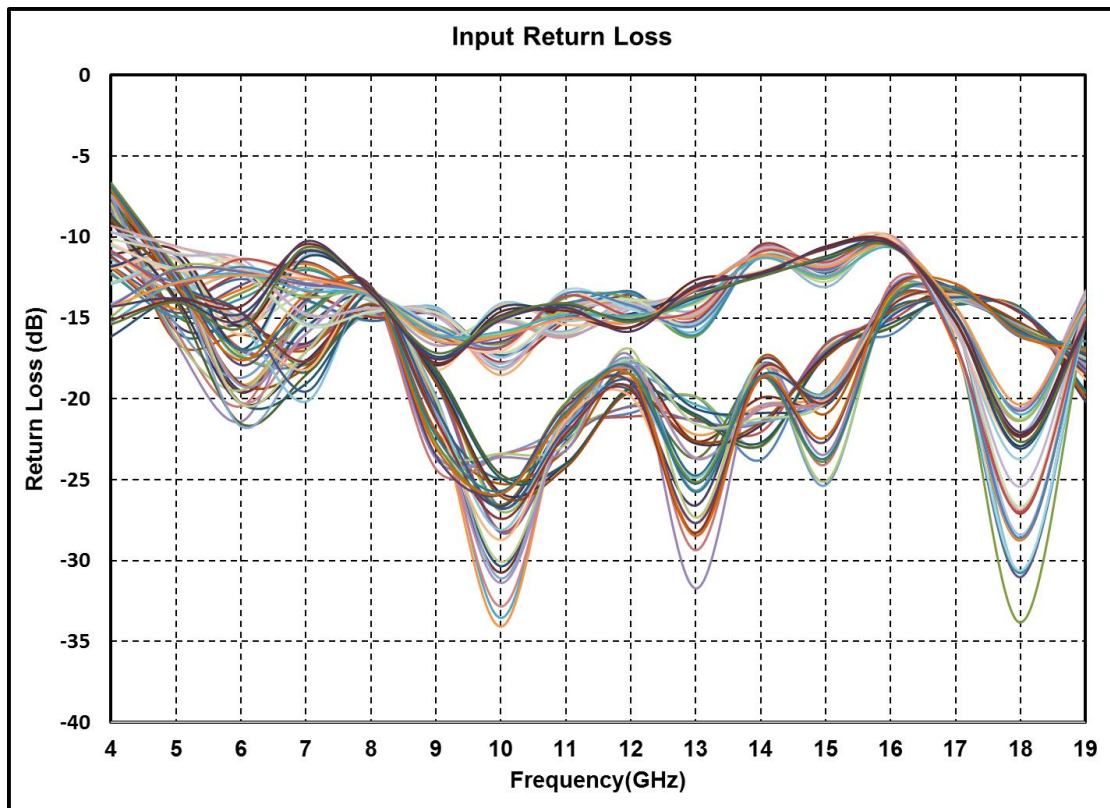
On Wafer data

Driver Bias +5V, -5V; Control Voltage 0/+5V; $T_A = 25^\circ\text{C}$



On Wafer data

Driver Bias +5V, -5V; Control Voltage 0/+5V; $T_A = 25\text{ }^{\circ}\text{C}$



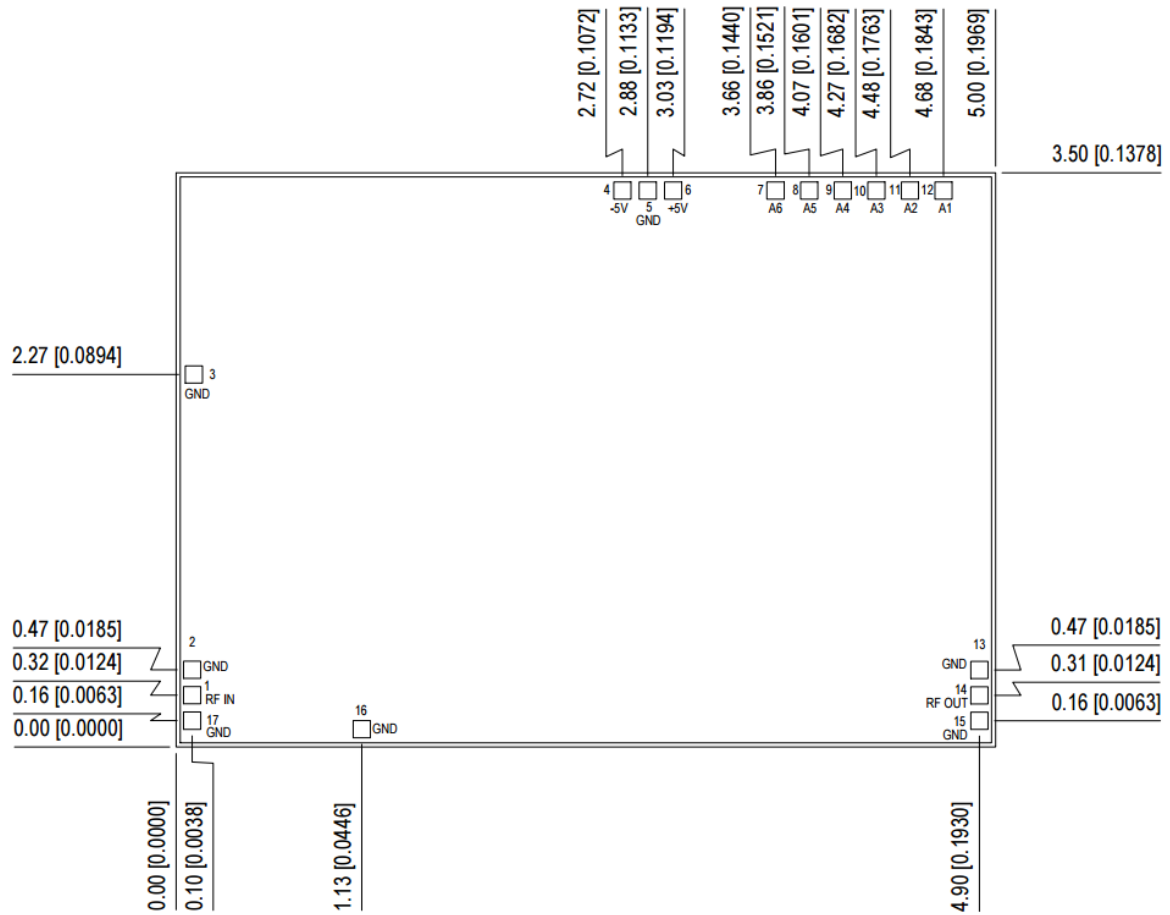
Truth Table

S.No.	Phase Shift	180Deg	90Deg	45Deg	22.5Deg	11.25Deg	5.625Deg
		A6	A5	A4	A3	A2	A1
1	0	0	0	0	0	0	0
2	5.625	0	0	0	0	0	1
3	11.25	0	0	0	0	1	0
4	16.875	0	0	0	0	1	1
5	22.5	0	0	0	1	0	0
6	28.125	0	0	0	1	0	1
7	33.75	0	0	0	1	1	0
8	39.375	0	0	0	1	1	1
9	45	0	0	1	0	0	0
10	50.625	0	0	1	0	0	1
11	56.25	0	0	1	0	1	0
12	61.875	0	0	1	0	1	1
13	67.5	0	0	1	1	0	0
14	73.125	0	0	1	1	0	1
15	78.75	0	0	1	1	1	0
16	84.375	0	0	1	1	1	1
17	90	0	1	0	0	0	0
18	95.625	0	1	0	0	0	1
19	101.25	0	1	0	0	1	0
20	106.875	0	1	0	0	1	1
21	112.5	0	1	0	1	0	0
22	118.125	0	1	0	1	0	1
23	123.75	0	1	0	1	1	0
24	129.375	0	1	0	1	1	1
25	135	0	1	1	0	0	0
26	140.625	0	1	1	0	0	1
27	146.25	0	1	1	0	1	0
28	151.875	0	1	1	0	1	1
29	157.5	0	1	1	1	0	0
30	163.125	0	1	1	1	0	1
31	168.75	0	1	1	1	1	0
32	174.375	0	1	1	1	1	1
33	180	1	0	0	0	0	0
34	185.625	1	0	0	0	0	1
35	191.25	1	0	0	0	1	0
36	196.875	1	0	0	0	1	1

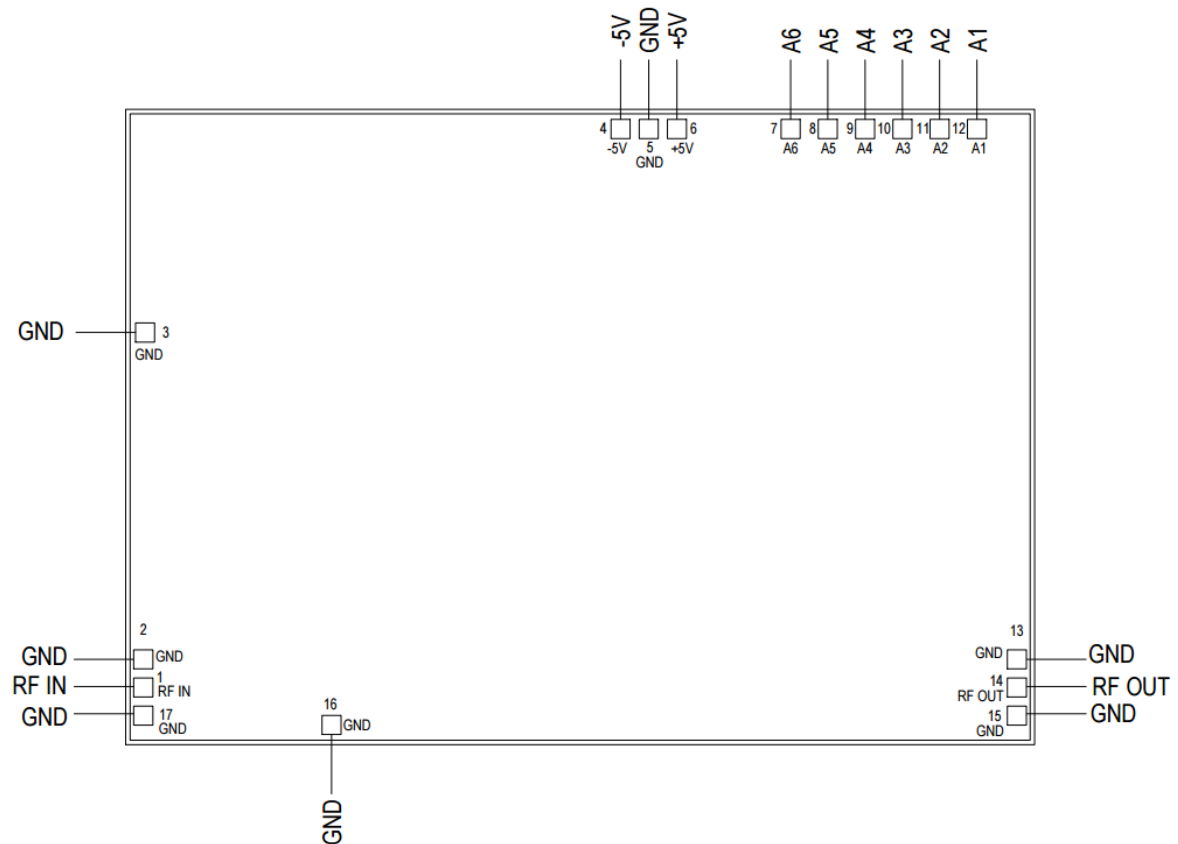
Truth Table

S.No.	Phase Shift	180Deg	90Deg	45Deg	22.5Deg	11.25Deg	5.625Deg
		A6	A5	A4	A3	A2	A1
37	202.5	1	0	0	1	0	0
38	208.125	1	0	0	1	0	1
39	213.75	1	0	0	1	1	0
40	219.375	1	0	0	1	1	1
41	225	1	0	1	0	0	0
42	230.625	1	0	1	0	0	1
43	236.25	1	0	1	0	1	0
44	241.875	1	0	1	0	1	1
45	247.5	1	0	1	1	0	0
46	253.125	1	0	1	1	0	1
47	258.75	1	0	1	1	1	0
48	264.375	1	0	1	1	1	1
49	270	1	1	0	0	0	0
50	275.625	1	1	0	0	0	1
51	281.25	1	1	0	0	1	0
52	286.875	1	1	0	0	1	1
53	292.5	1	1	0	1	0	0
54	298.125	1	1	0	1	0	1
55	303.75	1	1	0	1	1	0
56	309.375	1	1	0	1	1	1
57	315	1	1	1	0	0	0
58	320.625	1	1	1	0	0	1
59	326.25	1	1	1	0	1	0
60	331.875	1	1	1	0	1	1
61	337.5	1	1	1	1	0	0
62	343.125	1	1	1	1	0	1
63	348.75	1	1	1	1	1	0
64	354.375	1	1	1	1	1	1

Mechanical Characteristics



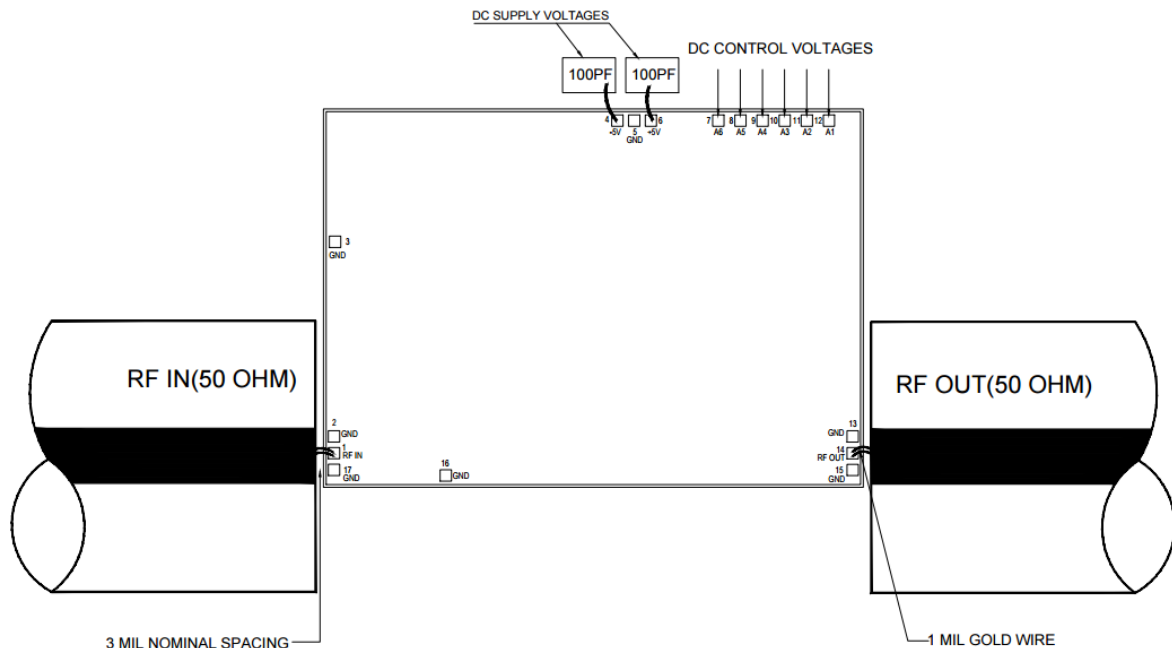
RF & DC Pad Details



Units : millimeters (inches)

1. All RF and DC bond pads are 100μm x 100μm in size
2. Pad no. 1 : RF IN
3. Pad no. 14 : RF OUT
4. Pad no. 4 : -5 V
5. Pad no. 6 : +5 V
6. Pad no. 7,8,9,10,11,12 : A6,A5,A4,A3,A2,A1 (Phase Controls)
7. Pad no. 2,3,5,13,15,17 : GND

Recommended Assembly Diagram



Note:

1. Two 1 mil (0.0254mm) bond wires of minimum length should be used for RF input and output.
2. The RF input & output ports are DC de – coupled.

Die attach: For Epoxy attachment, use of a two-component conductive epoxy is recommended. An epoxy fillet should be visible around the total die periphery. If Eutectic attachment is preferred, use of flux less AuSn (80/20) 1-2 mil thick preform solder is recommended. Use of AuGe preform should be strictly avoided.

Wire bonding: For DC pad connections use either ball or wedge bonds. For best RF performance, use of 150 - 200µm length of wedge bonds is advised. Single Ball bonds of 250-300µm though acceptable, may cause a deviation in RF performance.



GaAs MMIC devices are susceptible to Electrostatic discharge. Proper precautions should be observed during handling, assembly & testing

All information and Specifications are subject to change without prior notice. Please download and refer to datasheet from website before using the product.